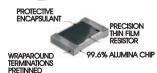


# State of the Art, Inc.

## Thin Film Chip Resistor M55342/12 RM0603

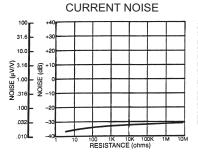


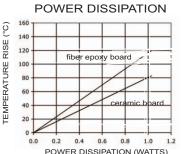
#### **PERFORMANCE**

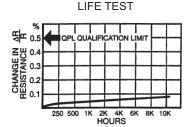
#### **CHARACTERISTICS\***

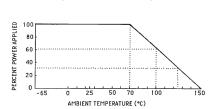
TESTS	<u>E</u>	<u>H</u>
TCR (-55 to +125 °C) in ppm/°C Thermal Shock Low Temperature Operation Short-time Overload Resistance to Soldering Heat Moisture Resistance Life, 2,000 Hours (qualification) High Temperature Exposure	±25 ±0.1% ±0.1% ±0.1% ±0.2% ±0.2% ±0.5% ±0.1%	±50 ±0.25% ±0.25% ±0.1% ±0.25% ±0.4% ±0.5% ±0.2%

<sup>\*</sup>Maximum allowable change per MIL-PRF-55342, typical change is 10% of these values.









POWER DERATING

### PART NUMBERING

#### M55342 H 12 B 100D R - TR

PACKAGING CODE: TR = Tape & Reel W= Waffle Pack

PRODUCT LEVEL DESIGNATOR: M: 1% per 1000 hrs. R: 0.01% P: 0.1% T: Space Level C: Non - ER

RESISTANCE AND TOLERANCE CODE:
Three significant digits, with a letter indicating the decimal location, the tolerance, and the value range.

A: 0.1%  $\Omega$  D: 1%  $\Omega$  G: 2%  $\Omega$  J: 5%  $\Omega$  B: 0.1%  $K\Omega$  E: 1%  $K\Omega$  H: 2%  $K\Omega$  K: 5%  $K\Omega$  C: 0.1%  $M\Omega$  F: 1%  $M\Omega$  T: 2%  $M\Omega$  L: 5%  $M\Omega$ 

TERMINATION MATERIALS: B: Solderable wraparound W: Gold wire bondable

SIZE CODE: /12 = RM0603

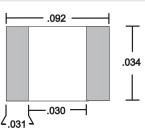
TEMPERATURE CHARACTERISTIC: E: ± 25ppm H: ± 50ppm

PERFORMANCE SPECIFICATION MIL-PRF-55342

#### **MECHANICAL**

	INCHES	MILLIMETERS	
Length Width Thickness Top Term Bottom Term Gap Approx. Weight	.062 (.058070) .032 (.027037) .018 (.010033) .010 (.007017) .014 (.010020) .034 (.030038) .00235 grams	1.58 (1.47 - 1.78) 0.81 (0.69 - 0.94) 0.46 (0.25 - 0.84) 0.25 (0.18 - 0.43) 0.36 (0.25 - 0.51) 0.86 (0.76 - 0.97)	

MINIMUM RECOMMENDED MOUNTING PADS (INCHES)



04/09/08